

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	600	imaging and (adhesive with (dam or barrier))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/06 15:34
S2	2	S1 and (restricting or impeding) with adhesive	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/16 11:13
S3	0	imaging and ((adhesive adj flow) with (dam or barrier))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/16 11:08
S4	8	semiconductor and ((adhesive adj flow) with (dam or barrier))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/16 11:12
S5	0	imaging and (transparent adj lens) and ((adhesive adj flow) with (dam or barrier))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/16 11:16
S6	0	S4 and transparent	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/16 11:11
S7	368	S1 and transparent	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/16 11:18
S8	0	S7 and semiconductor and ((adhesive adj flow) with (dam or barrier))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/16 11:12
S9	0	S7 and (restricting or impeding) with adhesive	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/19 13:31

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S10	4	S7 and groove with adhesive	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/06 15:33
S11	4	S7 and (groove with adhesive)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/16 11:14
S12	0	(transparent adj lens) and ((adhesive adj flow) with (dam or barrier))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/16 11:18
S13	0	(transparent with lens) and ((adhesive adj flow) with (dam or barrier))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/16 11:17
S14	0	(transparent with cover) and ((adhesive adj flow) with (dam or barrier))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/16 11:17
S15	0	(transparent with layer) and ((adhesive adj flow) with (dam or barrier))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/16 11:17
S16	0	(transparent adj lens) and ((adhesive with flow) with (dam or barrier))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/16 11:18
S17	368	S1 and transparent	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/16 11:25
S18	51	S17 and (transparent with (cover or lens))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/16 11:26
S19	12	S18 and (adhesive with (groove or trench))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/16 12:32

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S20	0	S19 and ((groove or trench) with curved)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/16 12:35
S21	0	S1 and ((groove or trench) with curved)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/16 12:35
S22	0	imaging and (adhesive with (groove or trench) with curved)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/16 12:37
S23	6	transparent and (adhesive with (groove or trench) with curved)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/16 12:37
S24	2	("6566745").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/15 19:01
S25	677	imaging and (adhesive with (dam or barrier))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/19 13:28
S26	404	S25 and transparent	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/19 13:43
S27	4	S26 and groove with adhesive	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/19 13:28
S28	31	((groove or trench) and (restricting or impeding)) with adhesive	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/06 15:16
S29	2	S28 and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/19 13:33

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S30	677	imaging and (adhesive with (dam or barrier))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/04 15:10
S31	203	S30 and die	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/19 14:43
S32	44	S31 and (die with adhesive)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/19 14:43
S33	9	imaging and (adhesive with trench)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/19 14:50
S34	415	(transparent with (cap or lid or cover or electrode) with (groove or trench or recess or gap or opening) with (adhesive or glue))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/04 14:28
S35	8	S34 and imaging	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/04 14:41
S36	260	(transparent with (lid or cover) with (groove or trench or recess or gap or opening) with (adhesive or glue))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/04 14:29
S37	46	(transparent with (lid or cover) with (groove or trench) with (adhesive))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/04 14:40
S38	0	S37 and imaging	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/04 14:30
S39	24	(transparent with (lid or cover)) and (adhesive with flow with (groove or trench))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/04 15:44

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S40	2	S39 and imaging	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/04 14:42
S41	15	imaging and (adhesive with (dam or barrier)) and (transparent with lid)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/04 15:33
S42	0	(adhesive with barrier with trench) and (transparent with lid)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/04 15:33
S43	0	(adhesive with barrier with trench) and (transparent with cover)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/04 15:34
S44	0	(adhesive with flow with trench) and (transparent with cover)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/04 15:34
S45	0	(adhesive with flow with trench) and (transparent with lid)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/04 15:34
S46	643	257/434.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/04 15:38
S47	2	S46 and (transparent with groove)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/04 15:42
S48	5	S46 and (cover with groove)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/04 15:45
S49	1	(transparent with (lid or cover)) and (encapsulant with flow with (groove or trench))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/04 15:44

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S50	11	encapsulant with (lid or cover) with (trench or groove)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/04 15:46
S51	0	(die or wafer) with (trench with adhesive with (restricts or restricting))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 13:15
S52	0	(die or wafer or chip or substrate) with (trench with adhesive with (restricts or restricting))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 13:15
S53	2	(die or wafer or chip or substrate) with (trench with adhesive with (restricts or restricting or restriction))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 13:15
S54	12	((groove or trench) with (wafer or chip or die or substrate)) and ((restricting or impeding) with (adhesive or epoxy))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/06 15:42
S55	18	((groove or trench or dam) with (wafer or chip or die or substrate)) and ((restricting or impeding) with (adhesive or epoxy))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/06 15:35
S56	1417	257/622.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/06 15:32
S57	1	S56 and (groove with adhesive)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/06 15:40
S58	1	S56 and (imaging and (adhesive with (dam or groove or trench or barrier)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/06 15:34
S59	40	((groove or trench or dam or barrier) with (wafer or chip or die or substrate)) and ((restricting or impeding) with (adhesive or epoxy))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/06 15:39

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S60	5	((groove or trench or dam or barrier) with (wafer or chip or die or substrate)) and ((restricting or impeding) with flow with (adhesive or epoxy))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/06 15:40
S61	1	groove with (adhesive or epoxy) with flow with (restrict or restricting)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/06 15:41
S62	3	((groove or trench) with (wafer or chip or die or substrate)) and (((restricting or impeding) with flow) with (adhesive or epoxy))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/06 15:43
S63	2	"6891236"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 18:10